Plastic coated metal plate prodn., used for printed circuit board - by coating metal plate with pulverised fine powder of synthetic resin and inorganic filler using electrostatic technique

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Abstract (Basic): JP 4367763 A

Synthetic resin and inorganic filler are mixed; the mixt. pulverised into fine powders and the fine powders coated over a metal plate to form an insulating layer by an electrostatic coating technique. Opt. a metal foil or another metal plate is put on the insulating layer and the whole assembly heated and pressed to produce a laminated plate.

Pref. a metal plate of Al, Cu, Zn, Fe, silicon steel or Fe-Ni alloy 0.2-0.5 mm thick is used. Polysulphone, polyphenylene sulphide, polyether etherketone, thermoplastic fluororesin, polyetherimide, epoxy resin, or polyimide resin is used for the coating layer, 50-300 microns thick. Inorganic fillers of silicon, aluminium or boron nitride of 0.1-10 microns dia. are pref. used.

USE/ADVANTAGE - Used to produce a metal plate with a synthetic resin coating. The resultant laminated plate has a good heat conductivity and is used as a baseplate for a printed circuit board.

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Title Terms: PLASTIC; COATING; METAL; PLATE; PRODUCE; PRINT; CIRCUIT; BOARD ; COATING; METAL; PLATE; PULVERISE; FINE; POWDER; SYNTHETIC; RESIN; INORGANIC; FILL; ELECTROSTATIC; TECHNIQUE
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